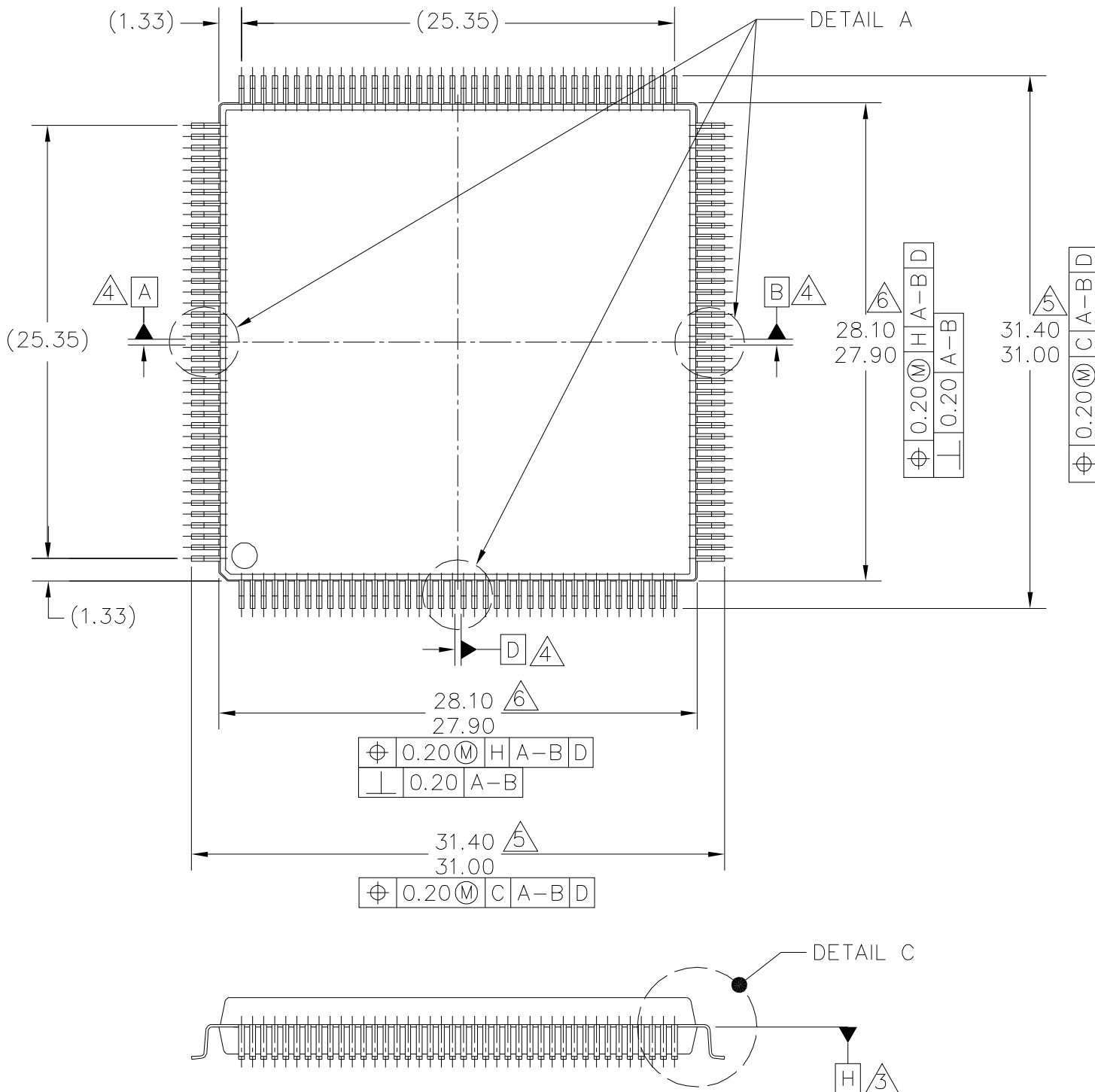
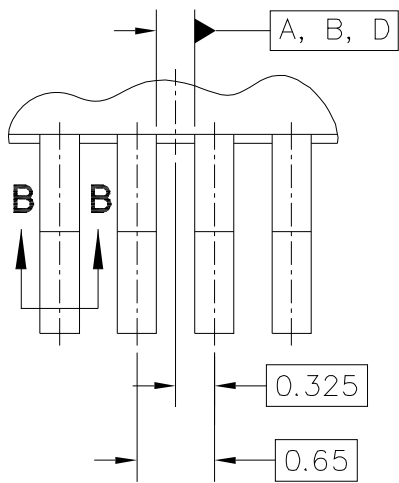
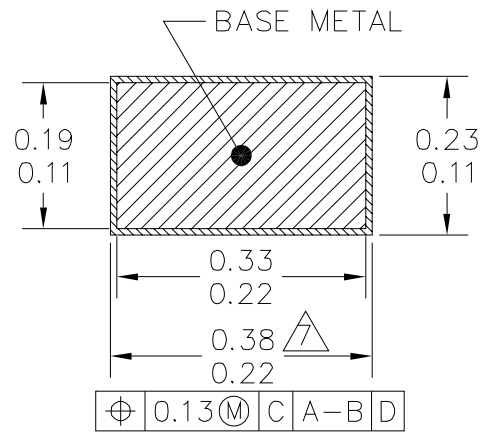




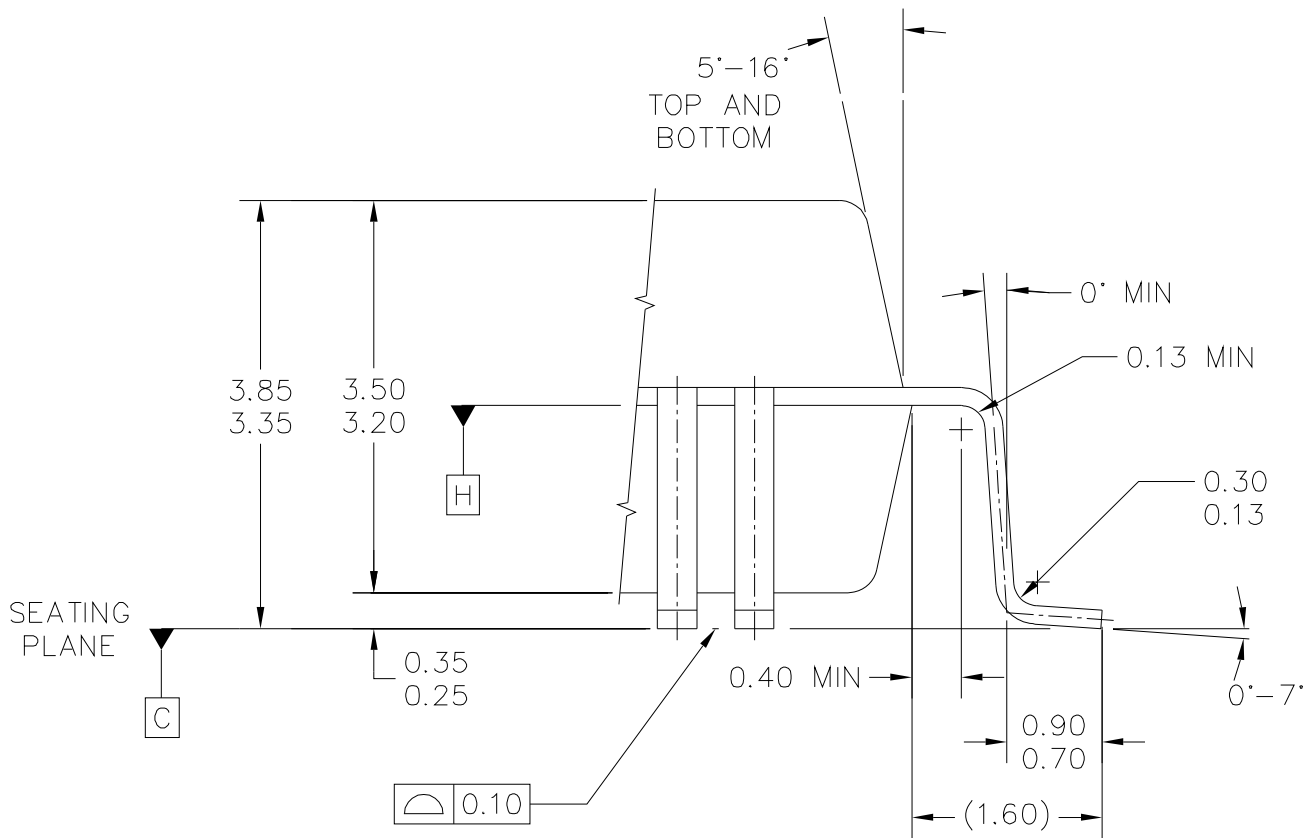
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TITLE: QUAD FLAT PACKAGE (QFP) 160 LEAD, 0.65 PITCH (28.00 X 28.00 X 3.30 PKG)			DOCUMENT NO: 98ASB42810B		REV: E
			CASE NUMBER: 864A-03		23 MAY 2005
			STANDARD: NON-JEDEC		



DETAIL A



SECTION B-B



DETAIL C

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			CASE NUMBER: 864A-03		23 MAY 2005
			STANDARD: NON-JEDEC		

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

2. CONTROLLING DIMENSION: MILLIMETER.

△ 3. DATUM PLANE IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.

△ 4. DATUMS TO BE DETERMINED AT DATUM PLANE H.

△ 5. DIMENSIONS TO BE DETERMINED AT SEATING PLANE C.

△ 6. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 PER SIDE. DIMENSIONS DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.

△ 7. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.

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